

















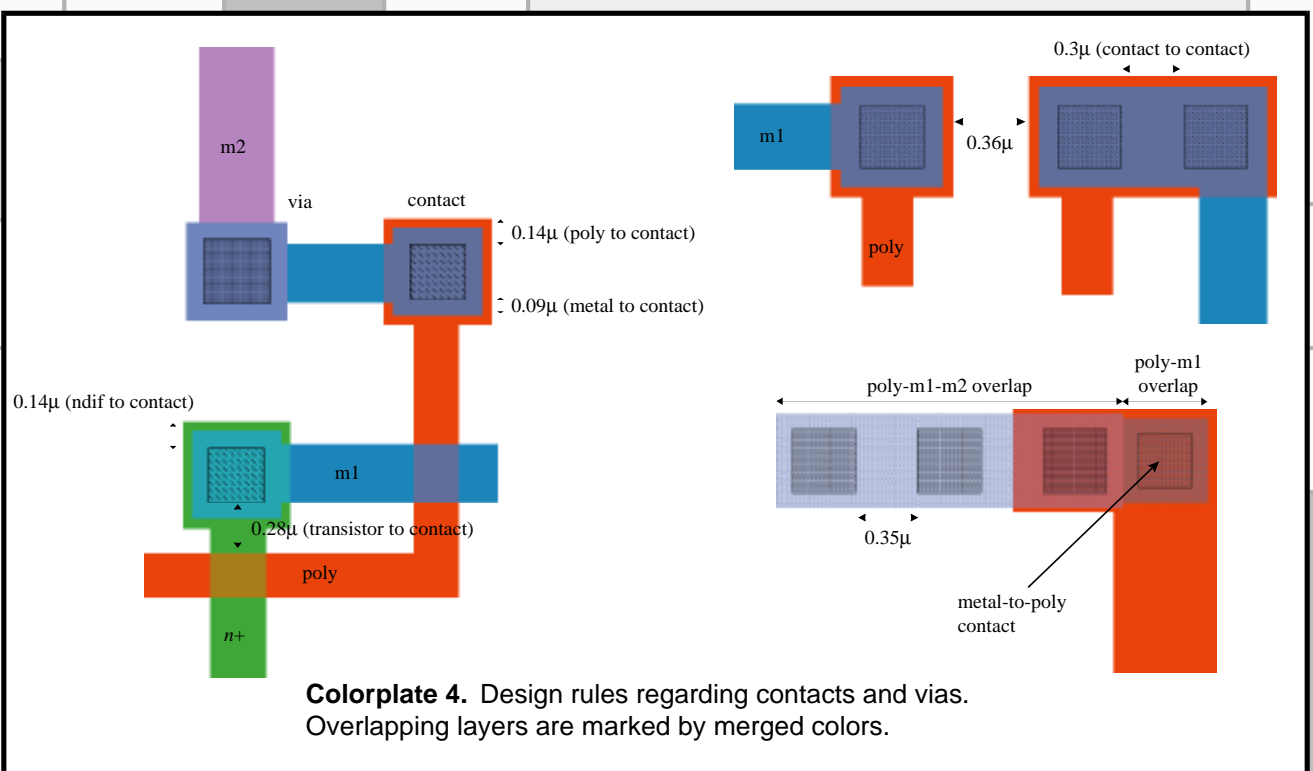
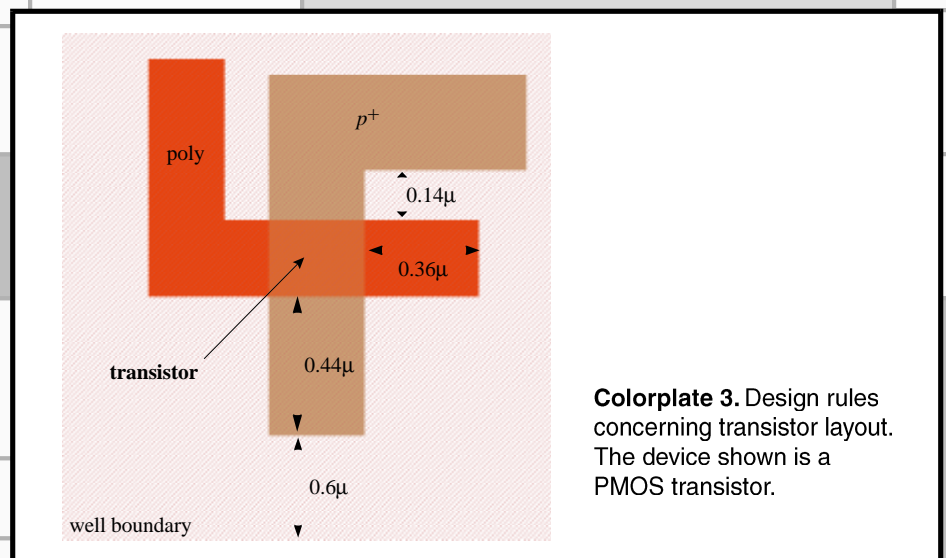
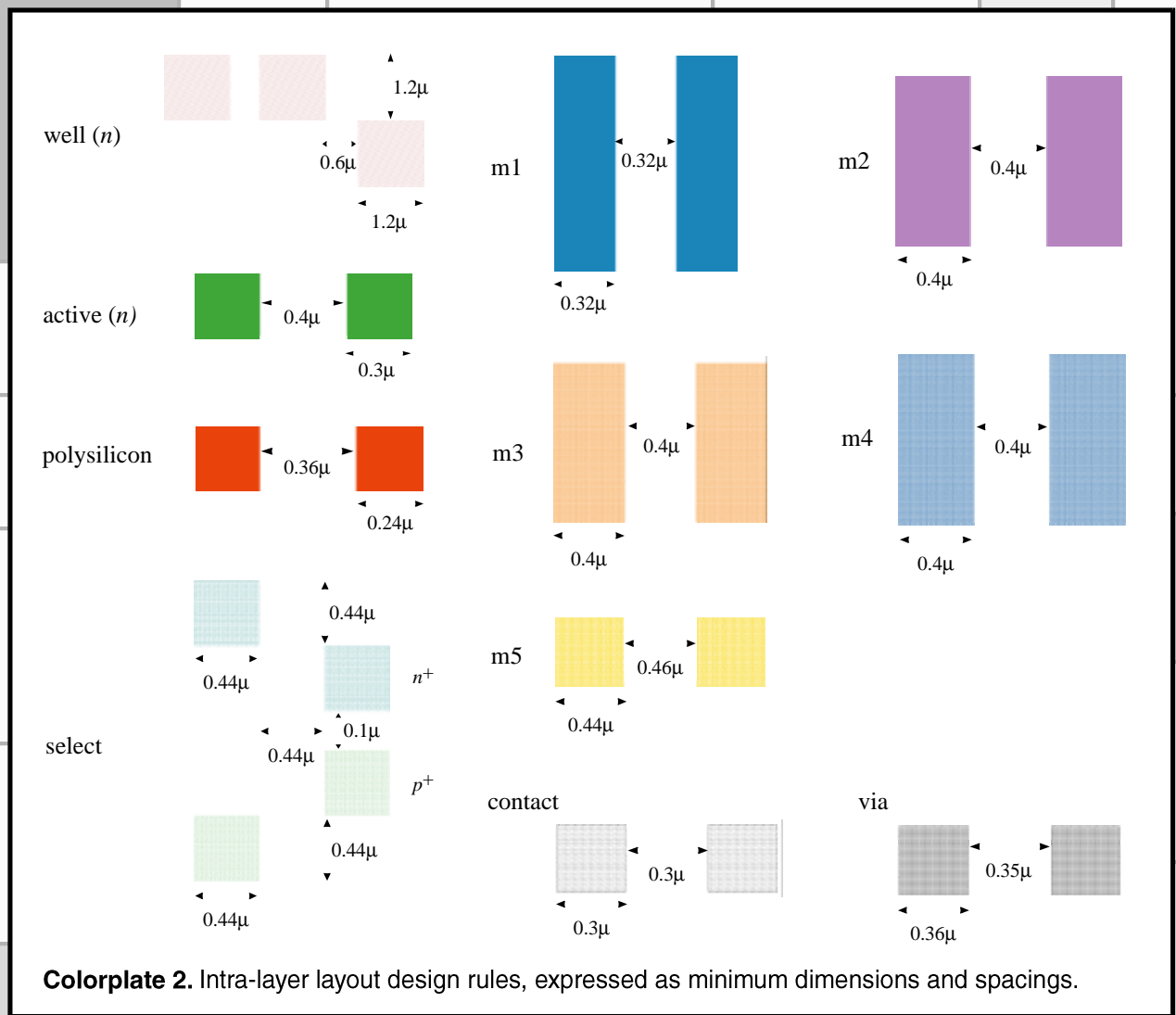


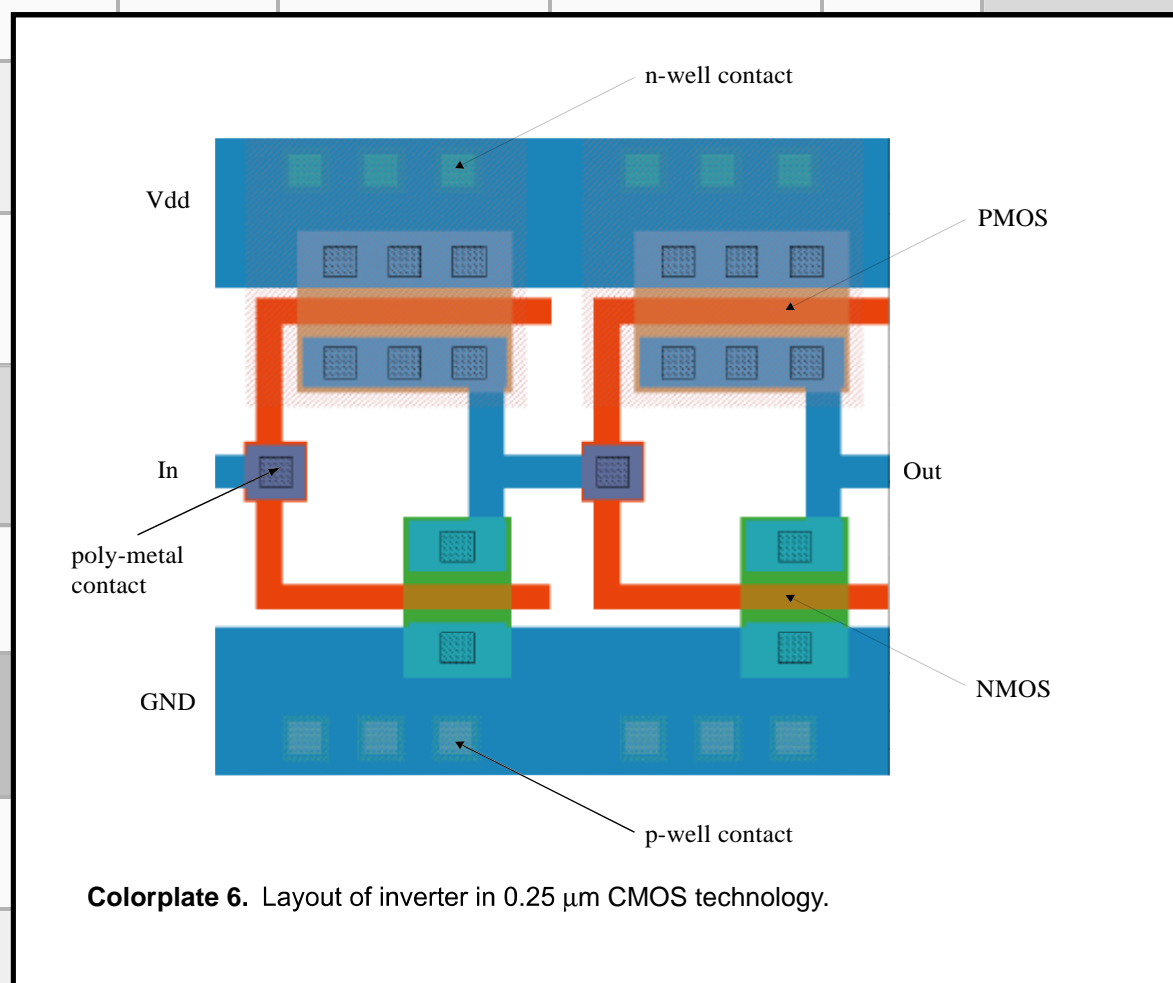
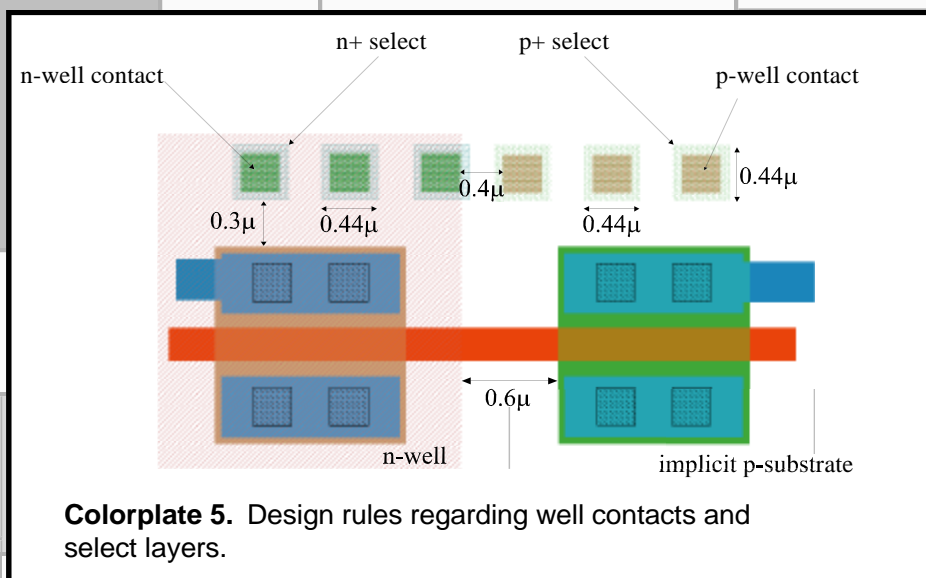
Layer Description	Representation				
metal	 m1	 m2	 m3	 m4	 m5
well	 nw				
polysilicon	 poly				
contacts & vias	 ct	 v12,v23,v34,v45	 nwc	 pwc	
active area and FETs	 ndif	 pdif	 nfet	 pfet	
select	 nplus	 pplus	 prb		

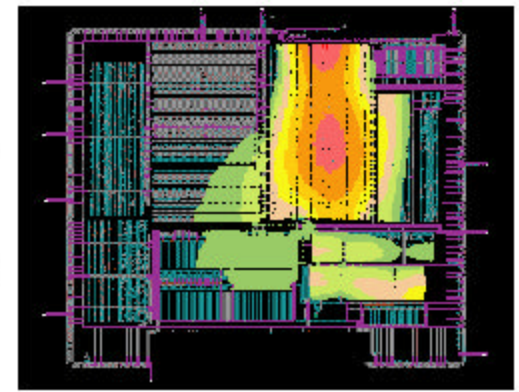
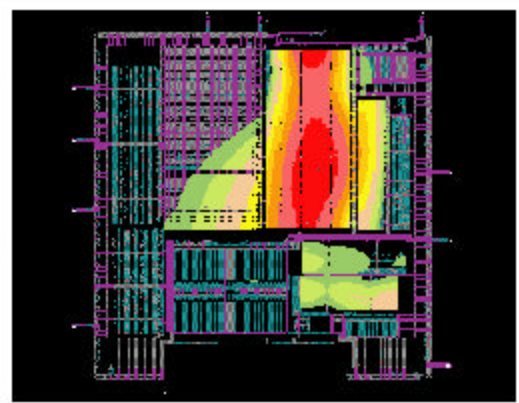
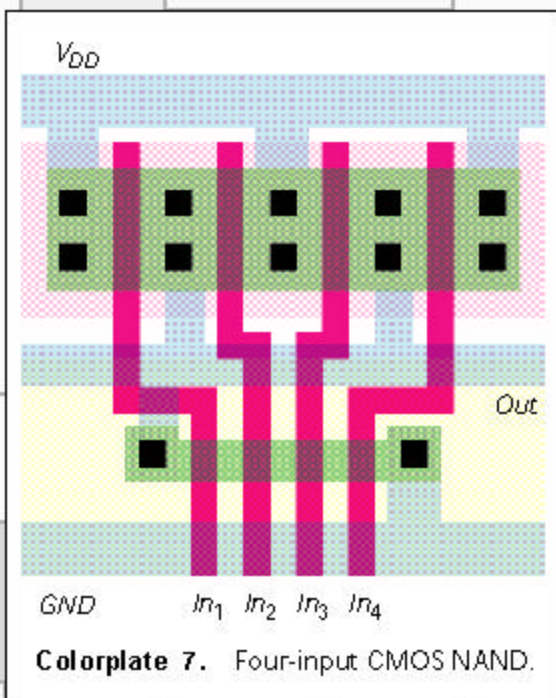
Colorplate 1. CMOS layers and representations
(for vanilla 0.25 μm CMOS process)



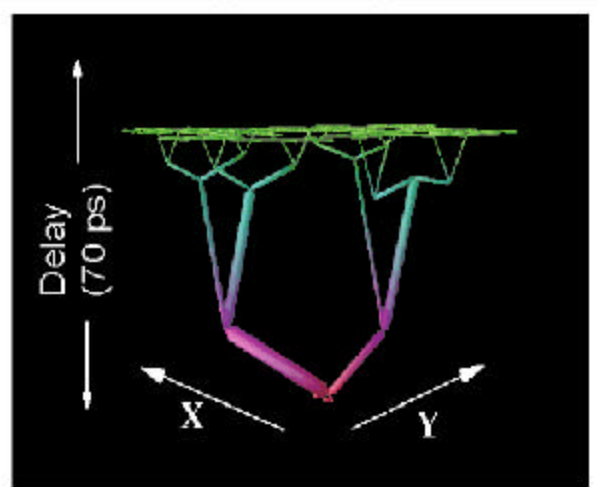
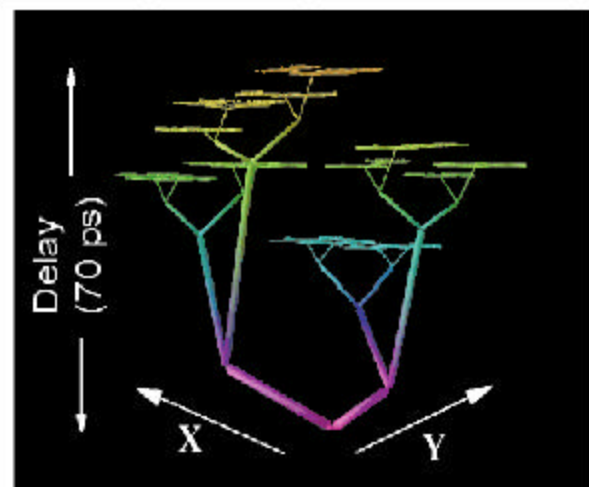
Colorplate 4. Design rules regarding contacts and vias.
Overlapping layers are marked by merged colors.







Colorplate 8. Simulated IR voltage drop in power-distribution network.



Colorplate 9. Visualizations of clock delay in a tree network driving different loads.